

### Amendments to the Claims

1. **(Original)** A semiconductor device comprising:  
a semiconductor element including an electrode formed on an electrode-formed surface thereof,  
a reinforcing member bonded to a back surface of said semiconductor element, said back surface being opposite to said electrode-formed surface; and  
an adhesive bonding said semiconductor element and said reinforcing member while allowing said semiconductor element to be deformed.
2. **(Original)** The semiconductor device of claim 1, wherein said adhesive is made of resin having a low elastic modulus, and bonds said back surface of said semiconductor element entirely to said reinforcing member.
3. **(Original)** The semiconductor device of claim 1, wherein said adhesive bonds only a center of said back surface of said semiconductor element to said reinforcing member.
4. **(Original)** The semiconductor device of claim 1, wherein said reinforcing member has a flexural rigidity greater than a flexural rigidity of said semiconductor element.
5. **(Original)** The semiconductor device of claim 1, wherein said reinforcing member is larger than said semiconductor element in outside shape.
6. **(Original)** The semiconductor device of claim 5, wherein said reinforcing member includes:  
a recess portion to which said semiconductor element is bonded; and  
a projection formed at a border of said recess portion.

7. **(Original)** The semiconductor device of claim 1, wherein said reinforcing member functions as a holding member in handling.

8. **(Currently Amended)** The semiconductor device of claim 1, wherein ~~an~~ identification information is applied to an applied surface of said reinforcing member, said applied surface being opposite to a surface of said reinforcing member bonded to said semiconductor element.

9. **(Currently Amended)** A method of manufacturing a semiconductor device, said comprising ~~the steps of~~:

shaving a back surface of a semiconductor wafer, the ~~said~~ back surface being opposite to an electrode-formed surface of the ~~said~~ semiconductor wafer including a plurality of semiconductor elements therein;

bonding a reinforcing plate to the shaved back surface of the semiconductor wafer with an adhesive; and

dividing the semiconductor wafer to which the reinforcing ~~member~~ plate is bonded and the reinforcing plate into units of the semiconductor elements, the reinforcing plate being operable to be held by a mounting head when the semiconductor elements are being mounted to a substrate.

10. **(Currently Amended)** The method of claim 9, wherein said ~~step of~~ dividing of the semiconductor wafer and the reinforcing plate comprises ~~includes the sub step of~~ dividing the reinforcing plate with a dicing width smaller than a dicing width of the semiconductor wafer.

11. **(Currently Amended)** The method of claim 9, further comprising ~~the step of~~ attaching a sheet to the electrode-formed surface of the semiconductor wafer, wherein said ~~step of~~ shaving of the back surface of the semiconductor wafer comprises ~~includes the sub step of~~ shaving the back surface of the semiconductor wafer while the sheet is attached to the electrode-formed surface of the semiconductor wafer.

12. **(Currently Amended)** The method of claim 9, further comprising ~~the step of~~ forming a bump on the electrode-formed surface of the semiconductor wafer.

13. **(Currently Amended)** A method of manufacturing a semiconductor device, said method comprising ~~the steps of~~:

forming a diced groove along a border between a plurality of semiconductor elements from an electrode-formed surface of a semiconductor wafer which includes the semiconductor elements formed therein;

attaching a sheet to the electrode-formed surface of the semiconductor wafer having the diced groove;

dividing the semiconductor wafer into the semiconductor elements ~~by through~~ shaving a back surface of the semiconductor wafer to thin the semiconductor wafer to a thickness until the shaved back surface reaches the diced groove, ~~the said~~ back surface being opposite to the electrode-formed surface to which the sheet is attached;

bonding a reinforcing plate to the back surface of the semiconductor elements with an adhesive; and

dividing the reinforcing plate into units corresponding to ~~of~~ the semiconductor elements after removing the sheet from the electrode-formed surface.

14. **(Currently Amended)** The method of claim 13, wherein said ~~step of~~ dividing of the reinforcing plate comprises ~~includes the sub-step of~~ dividing the reinforcing plate with a dicing width smaller than the diced groove of the semiconductor wafer.

15. **(Currently Amended)** A method of manufacturing a semiconductor device, said method comprising ~~the steps of~~:

shaving a back surface of a semiconductor wafer, the back surface being opposite to an electrode-formed surface of the semiconductor wafer which includes a plurality of semiconductor elements;

dividing the semiconductor wafer into the semiconductor elements; and

bonding a reinforcing member to a back surface of each of the semiconductor elements with an adhesive, the reinforcing member being operable to be held by a mounting head when the semiconductor elements are being mounted to a substrate.

16. **(Currently Amended)** The method of claim 15, further comprising ~~the step of~~ attaching a sheet to the electrode-formed surface of the semiconductor wafer, wherein said ~~step of shaving of~~ the back surface of the semiconductor wafer comprises ~~includes the sub-step of~~ shaving the back surface of the semiconductor wafer to which the sheet is attached.

17. **(Currently Amended)** The method of claim 15, further comprising ~~the step of~~ forming a bump on the electrode-formed surface of the semiconductor wafer.

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18. **(Currently Amended)** A method of mounting a semiconductor device which includes:  
a semiconductor element having an electrode-formed surface;  
a reinforcing member bonded to a back surface of the semiconductor element that allows ~~with allowing~~ the semiconductor element to be deformed, the back surface being opposite the electrode-formed surface; and  
an adhesive bonding the semiconductor element to the reinforcing member,  
said method comprising ~~the steps of~~:  
holding the reinforcing member; and  
mounting the semiconductor device to a workpiece, the semiconductor device having the reinforcing member held.

19. **(Currently Amended)** The method of claim 18,  
wherein the reinforcing member includes a recess portion to which the semiconductor element is bonded and a projection formed at a border of the recess portion, and  
wherein said ~~step of~~ mounting of the semiconductor device comprises ~~includes the sub-step of~~ bonding the projection to the workpiece.

20. (New) The semiconductor device of claim 1, wherein said semiconductor element has a thickness not greater than  $100\mu\text{m}$ .

21. (New) The method of claim 9, wherein said shaving of the back surface of the semiconductor wafer comprises shaving the back surface of the semiconductor wafer until the semiconductor wafer has a thickness of not greater than  $100\mu\text{m}$ .

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22. (New) The method of claim 13, wherein said shaving of the back surface of the semiconductor wafer comprises shaving the back surface of the semiconductor wafer until the semiconductor wafer has a thickness of not greater than  $100\mu\text{m}$ .

23. (New) The method of claim 15, wherein said shaving of the back surface of the semiconductor wafer comprises shaving the back surface of the semiconductor wafer until the semiconductor wafer has a thickness of not greater than  $100\mu\text{m}$ .

24. (New) The method of claim 18, wherein the semiconductor element has a thickness of not greater than  $100\mu\text{m}$ .

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